

Highlights

- Suitable for metals as well as hard materials, ceramics and workpieces with sharp edges
- All outside diameters possible
- Outstanding lifetime and economy compared to the competition
- New generation with50 % more grinding layer
- Cleaner than lapping with grinding suspensions
- High flatness, surface quality and precise edges

Diamond grinding pad

SQUADRO-M2/SQUADRO-H2

SQUADRO-M2 and SQUADRO-H2 are the second generation of the proven and highly efficient SQUADRO-M and SQUADRO-H diamond grinding pads. The highly innovative diamond grinding pads are optimized for fine grinding of metals, hard materials, ceramics, and workpieces with sharp edges. They combine all the advantages of SQUADRO-M and SQUADRO-H respectively.

The new, improved manufacturing process allows significantly greater flexibility in the production of different diameters and 50 % more grinding thickness. Accordingly, they offer a significantly better lifetime compared to the already outstanding lifetime of the previous generation. In terms of application, SQUADRO-M2 and SQUADRO-H2 offer high and uniform stock removal over the entire lifetime as well as impressive surface qualities and edge sharpening. Thanks to their long lifetime and easy handling, SQUADRO-M2 and SQUADRO-H2 are economical and efficient alternatives to other grinding pads or conventional lapping methods.

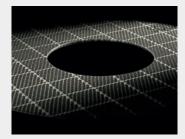
Typical applications

SQUADRO-M2: Fine grinding of metals

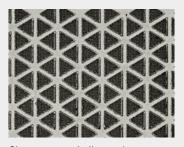
SQUADRO-H2: Fine grinding of hard materials, ceramics and sharp-edged workpieces

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PUREON



Diamond grinding pad SQUADRO.



Close-up on grinding pad SQUADRO.



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Product specifications

Abrasive layer thickness 0,6 mm

Bond type SQUADRO-M2: Resin, medium hard

SQUADRO-H2: Resin, hard

Carrier material Polycarbonate

Order information

Order code SQUADRO-M2 3-OD700-ID200mm-PU1-PSA-D1

O Diamond size 3 μm, 6 μm, 15 μm, 30 μm, 60 μm (125 µm only SQUADRO-H2)

For bigger diameters multi-piece

Custom sizes are available upon request Inner diameter Optional (freely selectable)

Backing / mounting PSA (self-adhesive)

SGM (metal plate) MAG (magnetic foil)

Optional

Application recommendations

Dressing Prior to the first use, the SQUADRO-M2 and SQUADRO-H2 pads have to be dressed and planarized with a dressing tool (e.g. Al₂O₃ with grit 280 mesh (grit size 60 µm, 125 µm) or 400 mesh (grit size $3 \mu m$, $6 \mu m$, $15 \mu m$, $30 \mu m$)).

Cleaning To ensure cutting efficiency of the bonding, the grinding pad has to be cleaned of abrasive debris regularly. Best suited for this are brass brushes for manual or machine use. Machine brushes can be

ordered from Pureon as accessories.

SQUADRO-LUB+ is recommended and a water-Coolant

> soluble cooling and lubricating fluid that ensures high and consistent material removal. DI-water is only partly suited. No dry running. Organic solvent and oil-based lubricants may harm the pad and are

therefore not recommended.

Grinding parameters

Grinding pressure Recommended: 2 – 10 N/cm2, max. 15 N/cm2

Circumferential speed Recommended: 5 m/s, max. 10 m/s



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